Polo scientifico tecnologico
Via Bovio 6 – 28100 Novara - NO - Italy
Tel +39 0321697200 - Fax +39 0321 688515 - Email: info@etneo.com
www.etneo.com

Precision BGA E2005 Rework System

Features:

1. No need for nozzles. No air flow during re-flow process.
2. Use non-contact infrared temperature sensor to real-timely measure temperature and achieve closed loop control of temperature during rework process, suitable for lead free process.
3. Reflecting foil can be used to reduce thermal transmission to adjacent components.
4. Can use process camera to monitor re-flow process of soldering joints during BGA rework process.
5. No air flow during the course of BGA re-balling; Nearly 100% successful BGA re-balling.

Specifications:

IR Infrared Rework System

Model	IR2005
General Power	1600Watt(max)
Power of Bottom Heater	400W*2=800Watt(Dark Infrared heating plate)
Power of Top Heater	180W*4=720Watt
	(Infrared heating tube, wavelength about 2-8μm)
Size of Top Heater	60*60mm
Size of Bottom Heater	135*250mm
Adjusting Range of Top Heater	20-60mm(X, Y direction both adjustable)
Vacuum Pump	12V/300mA, 0.05Mpa(max)
Top Cooling Fan:	12V/300mA, 15CFM
Laser Alignment Tube	3V/30Ma
Movable Motor	24V DC/100mA
Movable Arm Range	93mm
Max PCB Size	300mm*300mm
LCD Display Window	65.7*23.5mm 16*2 characters
Soldering Station	Intelligent Digital Lead Free Soldering Station
Soldering Power	60Watt
Communication	RS-232C(connect with PC)
Infrared Temperature Sensor	0-300℃(Testing Range)
Outside K-type Sensor	Optional
Weight	About 13kg

PL Precision Placement System

Model	PL2005
Power	About 15Watt
Camera	22*10 times magnifying; 12V/300mA
	Horizontal resolution: 480 lines; PAL format
Lens Size	40mm*40mm
Size of BGA to be aligned	40mm*40mm
Vacuum Pump	12V/600mA 0.05Mpa(max)
Camera Output Signal	Vedio Signal
Weight	22kg

RPC Reflow Soldering Process Camera

Model	RPC2005
Power	About 15Watt
Camera	22*10 times magnifying; 12V/300mA;
	Horizontal resolution: 480 lines; PAL format